Features□

Item:BEST-509 80g solder paste
BEST-solder (Tin) paste is the best choice of reballing IC .original ,Quality Verified
Use Range:laptop/computer/mobile phone/home Appliances SMD and BGA IC repairing
tools for chip-level repairing

Specification

White and plump solder joint, No False welding, Strong adhesive with solder iron tip .it's Indispensable tool for Accurate equipment repairing and Electronics Manufacture line.

PRODUCT DISPLAY





Name: Tin Paste Model: BST-509

Size: ϕ 36*35mm Weight: 80g

Composition: Sn63/Pb37 Melting point: 183°C



Storage:Chilled in refrigerator, the best refrigeration temperature is 5°C~10°C.

Features: 1. New technical support, unique chemical formula provides excellent wettability, ensuring high reliability.

- 2. Use highly effective thixotropic agents to effectively prevent the collapse of printing and preheating, and ensure good printing and fine pattern.
- 3. More advanced thermal insulation technology, adhesive durability, not easy to dry, sticky time up to 48 hours.
- 4. High quality, unique formulation, perfect performance, easy to weld, bright and full of welding spot, no such phenomenon as false welding or false welding.
- The residue is colorless and transparent. It does not affect the monitoring, cleaning and cleaning performance.
- 6. Good moisturizing and dry resistance. Under normal temperature, the shelf life is longer, which is suitable for mobile phone maintenance, computer digital maintenance industry, high precision circuit board SMT welding, BGA process welding, etc.







